

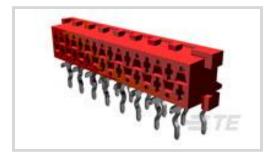
Micro-MaTch | Micro-MaTch Industrial

TE Internal #: 7-215460-6 Ribbon Cable Connectors, Cable-to-Board, 6 Position, 2.54 mm [.1 in] Centerline, Right Angle, Through Hole - Solder, 2 Row, Micro-MaTch Industrial

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Connectors > PCB Connectors > Wire-to-Board Connectors > FFC, FPC & Ribbon Connectors > Ribbon Cable Connectors



Connector System: Cable-to-Board

Number of Positions: 6

Centerline (Pitch): 2.54 mm [.1 in]

PCB Mount Retention: With

PCB Mount Retention Type: Kinked Legs

Features

Product Type Features

Ribbon Cable Connector Type

Connector Product Type

Connector System

Female-on-Board

Connector Assembly

Cable-to-Board

Connector & Housing Type	Receptacle
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Number of Positions	6
PCB Mount Orientation	Right Angle
Number of Rows	2
Electrical Characteristics	
Insulation Resistance	1000 MΩ
Operating Voltage	100 VAC
Body Features	
Primary Product Color	Red
Connector Profile	Standard
Contact Features	
PCB Contact Termination Area Plating Material Thickness	3 – 5 μm[118.11 – 196.85 μin]
Contact Layout	Staggered

C For support call+1 800 522 6752

Ribbon Cable Connectors, Cable-to-Board, 6 Position, 2.54 mm [.1 in] Centerline, Right Angle, Through Hole - Solder, 2 Row, Micro-MaTch Industrial



Contact Type Receptacle Contact Mating Area Plating Material Tin PCR Contact Termination Area Plating Material Finish Matte Contact Mating Area Plating Material Finish Matte Contact Mating Area Plating Material Finish Matte Contact Underplating Material Finish Matte Contact Underplating Material Tin Contact Termination Area Plating Material Tin Contact Current Rating (Max) 1.5 A Termination Method to Printed Circuit Roard Through Hale - Solder Mating Alignment With PCB Mount Retention With PCB Mount Retention With PCB Mount Retention Without PCB Mount Retention Side Planing Inspin Contact Side Posing First Prese Side Planing Mat		
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PCB Mount Retention With PCB Mount Retention Type Kinked Legs Mating Alignment Type Polarization Mating Retention Without Connector Mounting Type Board Mount Housing Features Board Mount Mating Entry Location Side Housing Material Glass Filled PBT Centerline (Pitch) 2.54 mm[.059 in] Dimensions I.5 mm[.059 in] Vage Conditions -40 – 105 °C[-40 – 221 °F] Operating Temperature Range -40 – 105 °C[-40 – 221 °F] Circuit Application Signal Industry Standards Signal	Mating Alignment	With
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Housing Features Mating Entry Location Side Housing Material Glass Filled PBT Centerline (Pitch) 2.54 mm[.1 in] Dimensions I.5 mm[.059 in] Row-to-Row Spacing 1.5 mm[.059 in] Usage Conditions -40 - 105 °C[-40 - 221 °F] Operating Temperature Range -40 - 105 °C[-40 - 221 °F] Circuit Application Signal	Mating Retention	Without
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Housing Material Glass Filled PBT Centerline (Pitch) 2.54 mm[.1 in] Dimensions Image: Conditions Row-to-Row Spacing 1.5 mm[.059 in] Usage Conditions -40 – 105 °C[-40 – 221 °F] Operating Temperature Range -40 – 105 °C[-40 – 221 °F] Operation/Application Signal Industry Standards Signal	Housing Features	
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Dimensions Row-to-Row Spacing 1.5 mm[.059 in] Usage Conditions Operating Temperature Range -40 – 105 °C[-40 – 221 °F] Operation/Application Circuit Application Industry Standards	Housing Material	Glass Filled PBT
Row-to-Row Spacing 1.5 mm[.059 in] Usage Conditions Operating Temperature Range -40 – 105 °C[-40 – 221 °F] Operation/Application Circuit Application Industry Standards	Centerline (Pitch)	2.54 mm[.1 in]
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Operating Temperature Range -40 – 105 °C[-40 – 221 °F] Operation/Application -40 – 105 °C[-40 – 221 °F] Circuit Application Signal Industry Standards	Row-to-Row Spacing	1.5 mm[.059 in]
Operation/Application Circuit Application Industry Standards	Usage Conditions	
Circuit Application Signal Industry Standards	Operating Temperature Range	-40 – 105 °C[-40 – 221 °F]
Industry Standards	Operation/Application	
	Circuit Application	Signal
UL Rating Recognized	Industry Standards	
	UL Rating	Recognized
Agency/Standard UL	Agency/Standard	UL

Ribbon Cable Connectors, Cable-to-Board, 6 Position, 2.54 mm [.1 in] Centerline, Right Angle, Through Hole - Solder, 2 Row, Micro-MaTch Industrial



Approved Standards	UL E28476
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Quantity	250
Packaging Method	Box
Product Compliance For compliance documentation, visit the product page on TE.com>	
EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JAN 2023 (233) Does not contain REACH SVHC
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Wave solder capable to 265°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

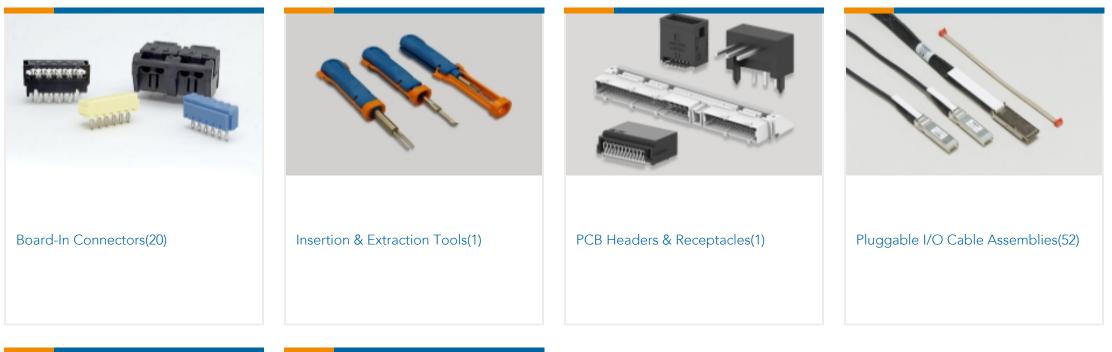
Compatible Parts

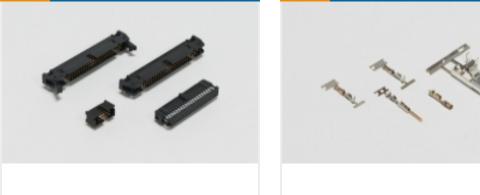
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Also in the Series Micro-MaTch Industrial

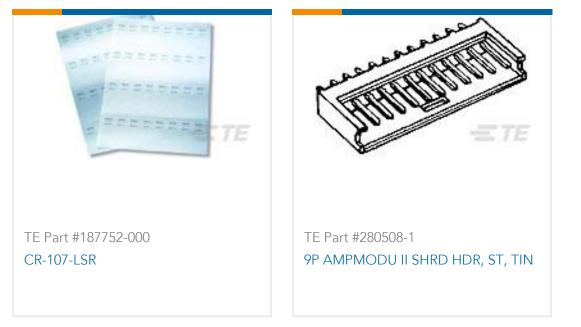






Customers Also Bought





Ribbon Cable Connectors, Cable-to-Board, 6 Position, 2.54 mm [.1 in] Centerline, Right Angle, Through Hole - Solder, 2 Row, Micro-MaTch Industrial



Documents

Product Drawings MICRO-MATCH FSID P

English

CAD Files

3D PDF

3D

Customer View Model ENG_CVM_CVM_7-215460-6_J.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_7-215460-6_J.3d_igs.zip

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Customer View Model

ENG_CVM_CVM_7-215460-6_J.3d_stp.zip

English

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Datasheets & Catalog Pages

Micro-MaTch Catalog

English

Ribbon Cable Interconnect Solutions

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Centerline Micro-Match Connector Series

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Product Specifications Product Specification

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Product Environmental Compliance MD_7-215460-6_12302013634_dmtec

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Agency Approvals UL Report

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